2024 Taiwan ESD and Reliability Conference

Dates: Oct. 30 - Nov. 1, 2024
Location: National Yang Ming Chiao Tung University, Hsinchu, Taiwan
Organizer: Taiwan ESD Association
Conference Website: http://www.alab.iee.nycu.edu.tw/~esd/TESDC/

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Call for Papers

Electrostatic Discharge (ESD) and reliability are critical issues for IC products with increased complexity in various processes. In order to improve the ESD and reliability related R&D capability, Taiwan ESD and Reliability Conference is going to be held, which is technically sponsored by Taiwan ESD Association (T-ESDA). Disclosures on ESD and reliability related experiences and research results are welcome, so that practical discussions and solutions can be obtained. Through the communications provided by this conference, the principles of the practical world experiences will be explained.

This conference focuses on the ESD protection and reliability related technologies. Papers related to the studies on analysis and solutions for practical cases are specifically interested. **Topics of interest include, but are not limited to:**

※ Component Level ESD Issue
※ System-Level ESD/EMI Issue
※ Factory-Level ESD Issue
※ EDA Verification
※ ESD Materials Technology
※ ESD Testing – Components, System, Factory & Materials
※ Reliability and Product Failure Analysis
※ Recent Patents on ESD and Reliability

Information for Authors

1. Papers should be accomplished in A4 paper size. It should be in a camera-ready format. The submission shall be made electronically (in PDF format).
2. Paper Submission Deadline: Aug. 30, 2024
3. Paper Acceptance Announcement: Sep. 30, 2024
4. About the paper format and the most updated news release, please visit URL http://www.alab.iee.nycu.edu.tw/~esd/TESDC/